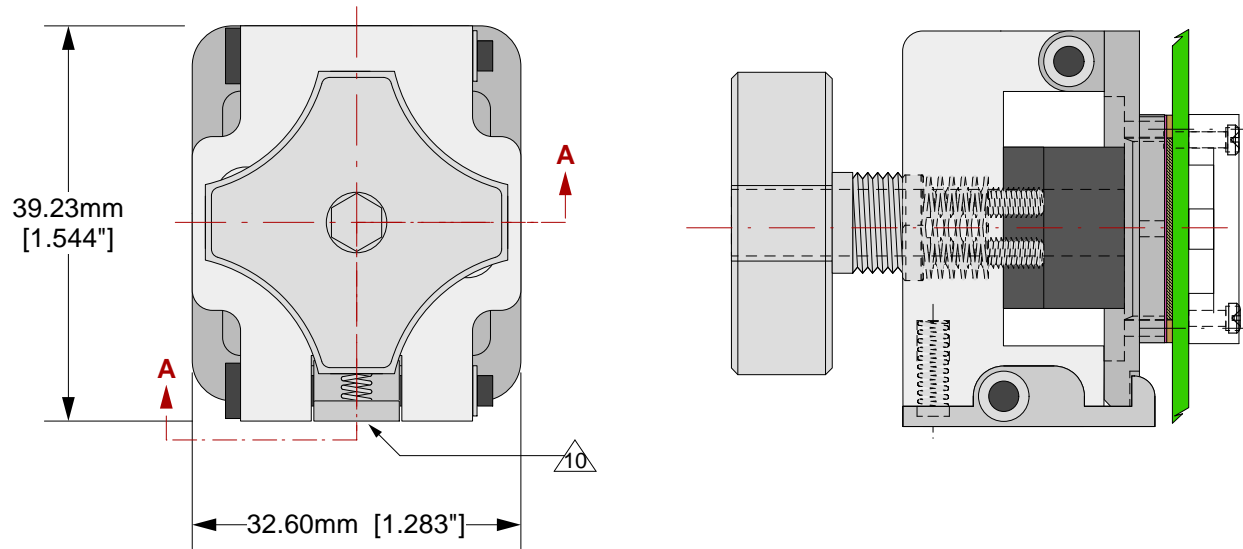
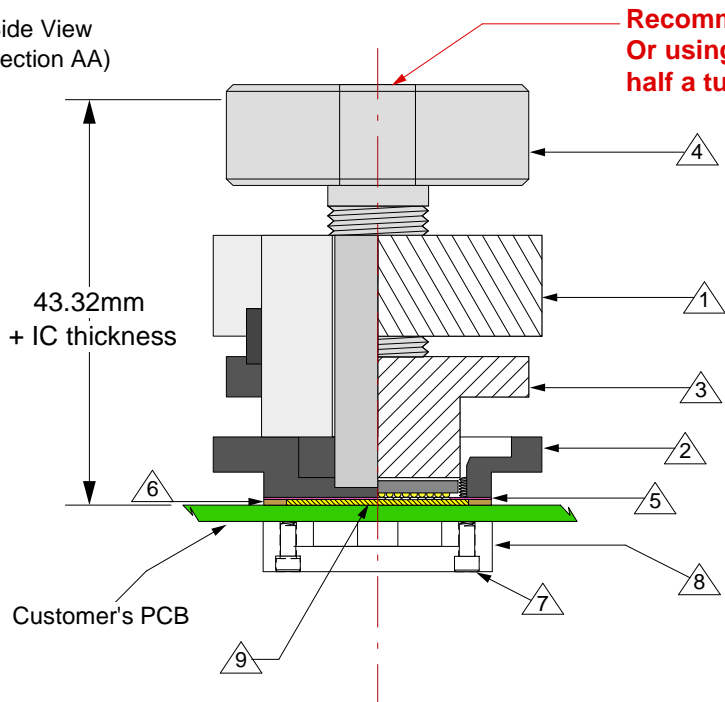


Top View



Side View
(Section AA)




Features

- Directly mounts to target PCB (needs tooling holes) with hardware.
- Minimum real estate required
- Compression plate distributes forces evenly
- Clamshell lid
- Minimum real estate required
- High speed, reliable Elastomer connection

Materials:

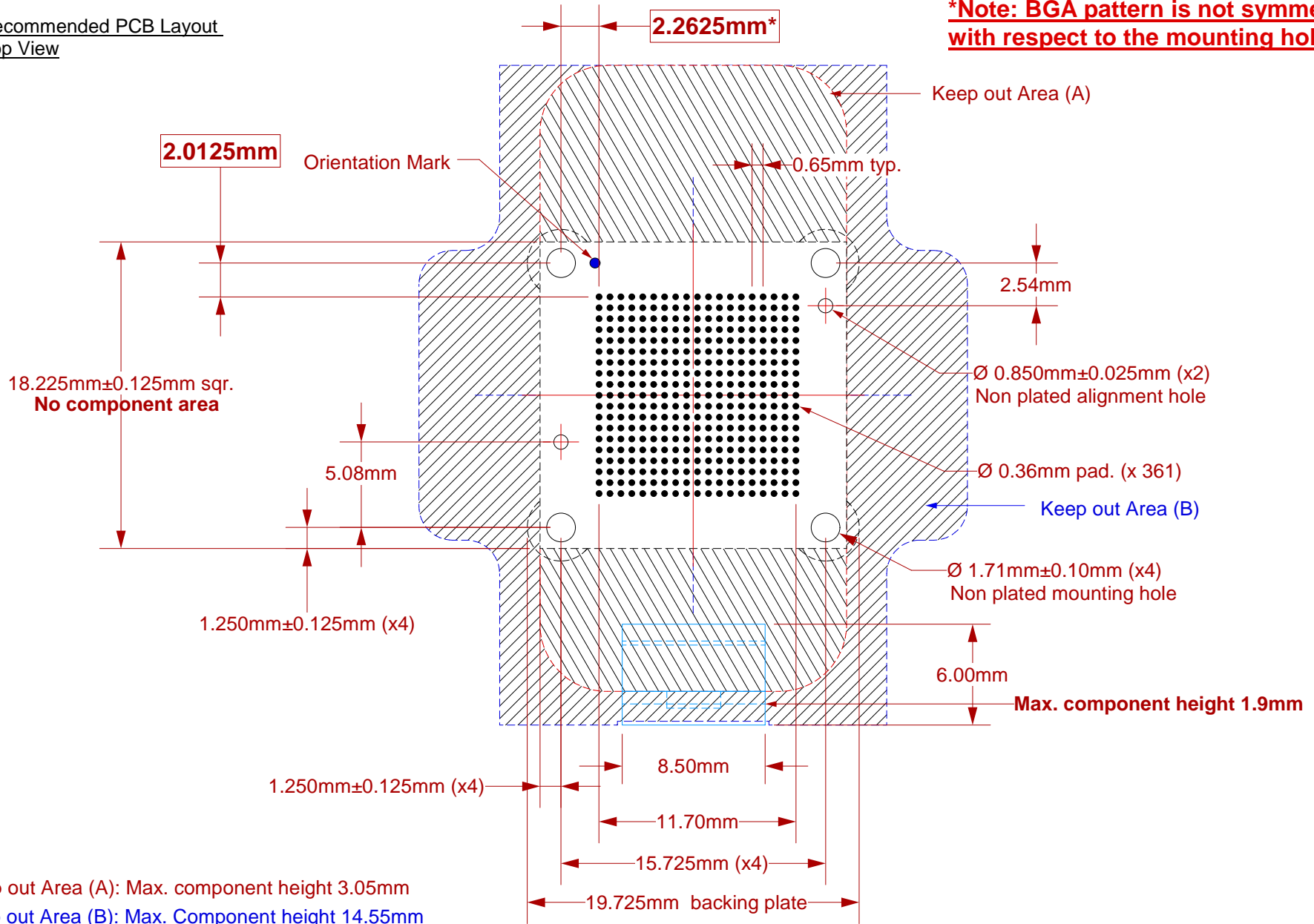
- 1 Clam Shell Lid: Black anodized Aluminum. Height = 20 mm.
- 2 Socket Base: Black anodized Aluminum. Height = 6 mm.
- 3 Compression Plate: Black anodized Aluminum. Thickness = 12 mm.
- 4 Compression Screw: Clear anodized Aluminum. Height = 27 mm, Fluted Knob
- 5 Ball guide: Kapton
- 6 Elastomer Guide: Ultem 1000. Thickness: 0.425mm
- 7 Socket Base Screw: Socket Head Cap Screw, alloy steel with black oxide finish, 0-80 Thread, 3/8" long.
- 8 Backing Plate: Black anodized Aluminum
- 9 Elastomer: 20 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.5mm.
- 10 Latch: Black anodized Aluminum.

CG-BGA-5008 Drawing		Status: Released	Scale: 1.25:1	Rev: A
 <p>© 2012 IRONWOOD ELECTRONICS, INC. Tele: (952) 229-8200 www.ironwoodelectronics.com</p>	Drawing: E Smolentseva		Date: 10/22/12	
	File: CG-BGA-5008 Dwg		Modified:	

All Tolerances: ±0.125mm (unless stated otherwise). Materials and specifications are subject to change without notice.

Recommended PCB Layout
Top View

***Note: BGA pattern is not symmetrical with respect to the mounting holes.**



Keep out Area (A): Max. component height 3.05mm


Keep out Area (B): Max. Component height 14.55mm

Target PCB Recommendations

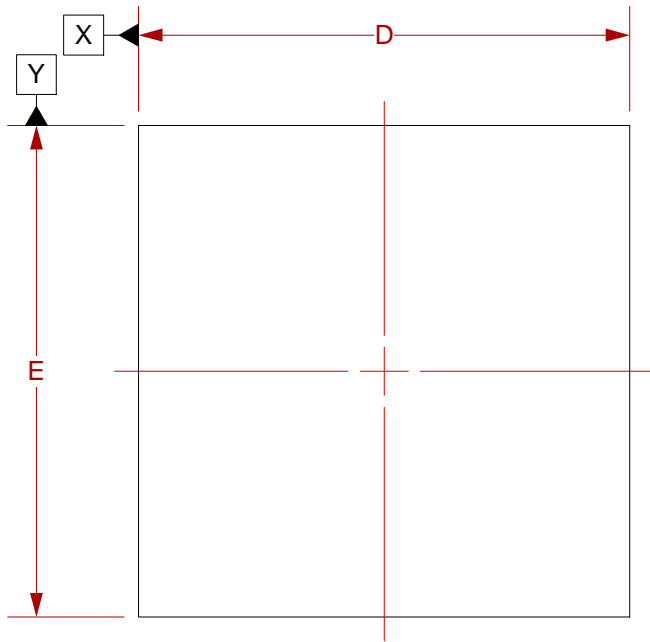
Total thickness: 1.5mm min.

Plating: Gold or Solder finish

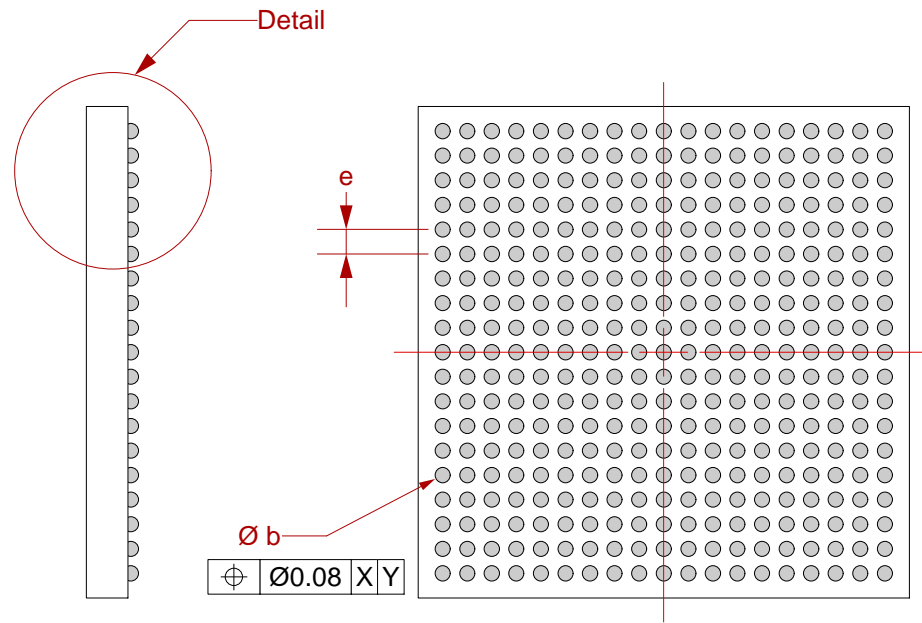
DXF DATA WILL BE PROVIDED

	CG-BGA-5008 Drawing	Status: Released	Scale: 1.25:1	Rev: A
	© 2012 IRONWOOD ELECTRONICS, INC. Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: E Smolentseva		Date: 10/22/12
		File: CG-BGA-5008 Dwg	Modified:	

Recommended PCB Layout Tolerances:
±0.025mm [±0.001"] unless stated otherwise.

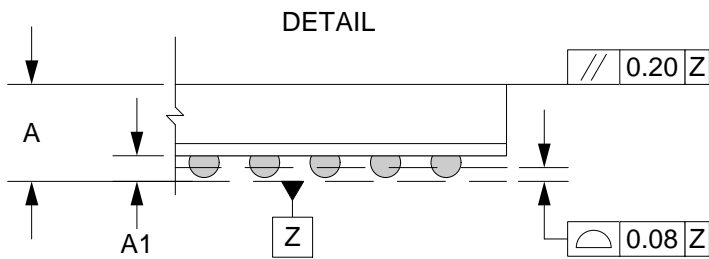
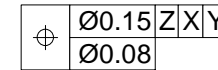


Top View



Side View

Bottom View




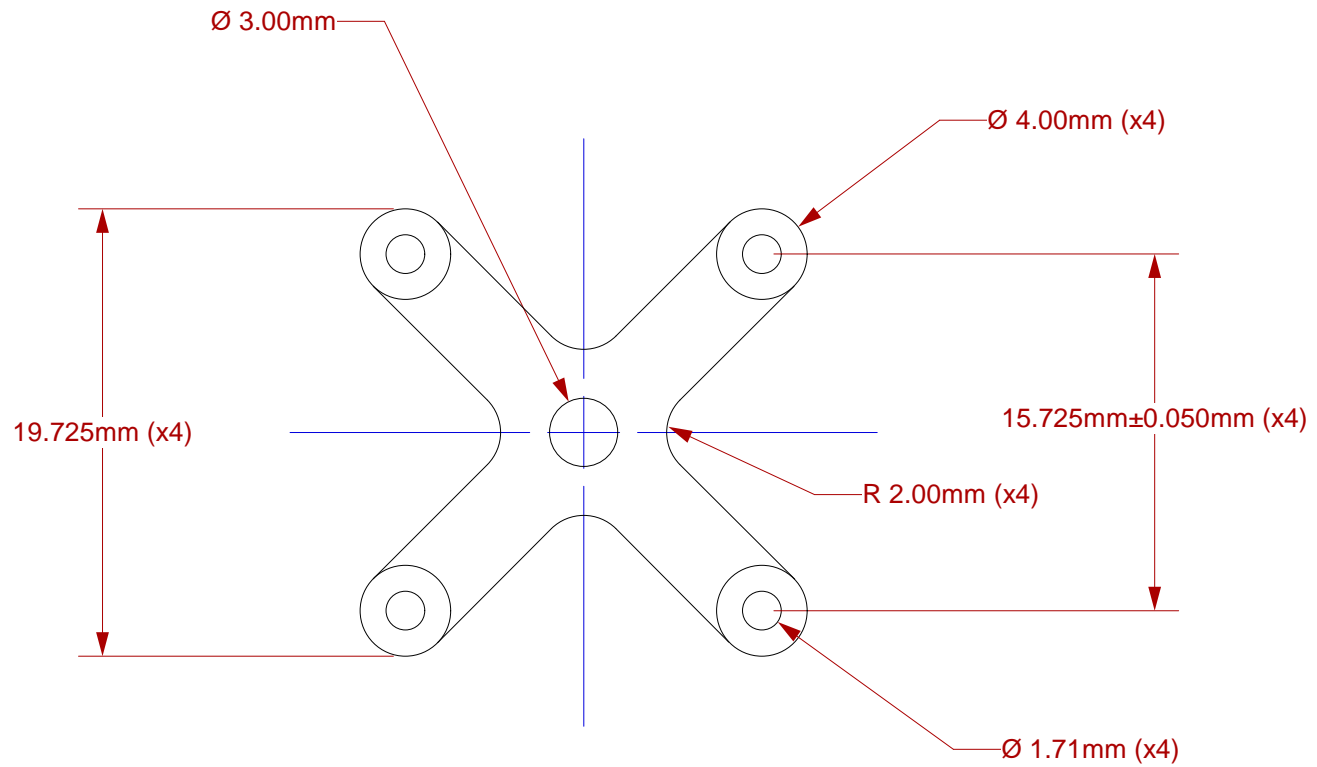
1. Dimensions are in millimeters.
2. Interpret dimensions and tolerances per ASME Y14.5M-1994.

- 3. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
- 4. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
- 5. Parallelism measurement shall exclude any effect of mark on top surface of package.

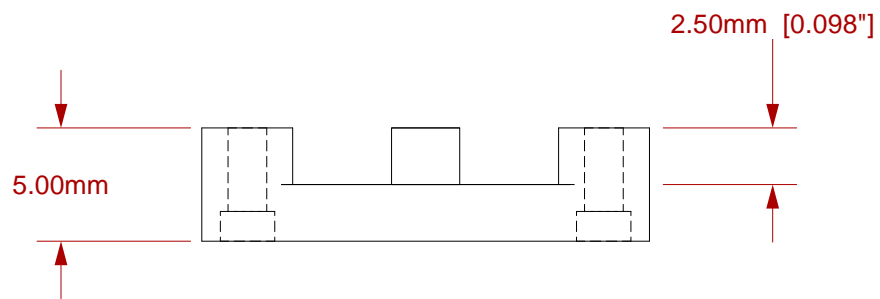
DIM	MIN	MAX
A		1.4
A1	0.25	0.3
b		0.45
D	13.0 BSC	
E	13.0 BSC	
e	0.65 BSC	

19 x 19 array

	CG-BGA-5008 Drawing	Status: Released	Scale: 1.25:1	Rev: A
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		File: CG-BGA-5008 Dwg	Modified:	



Top View

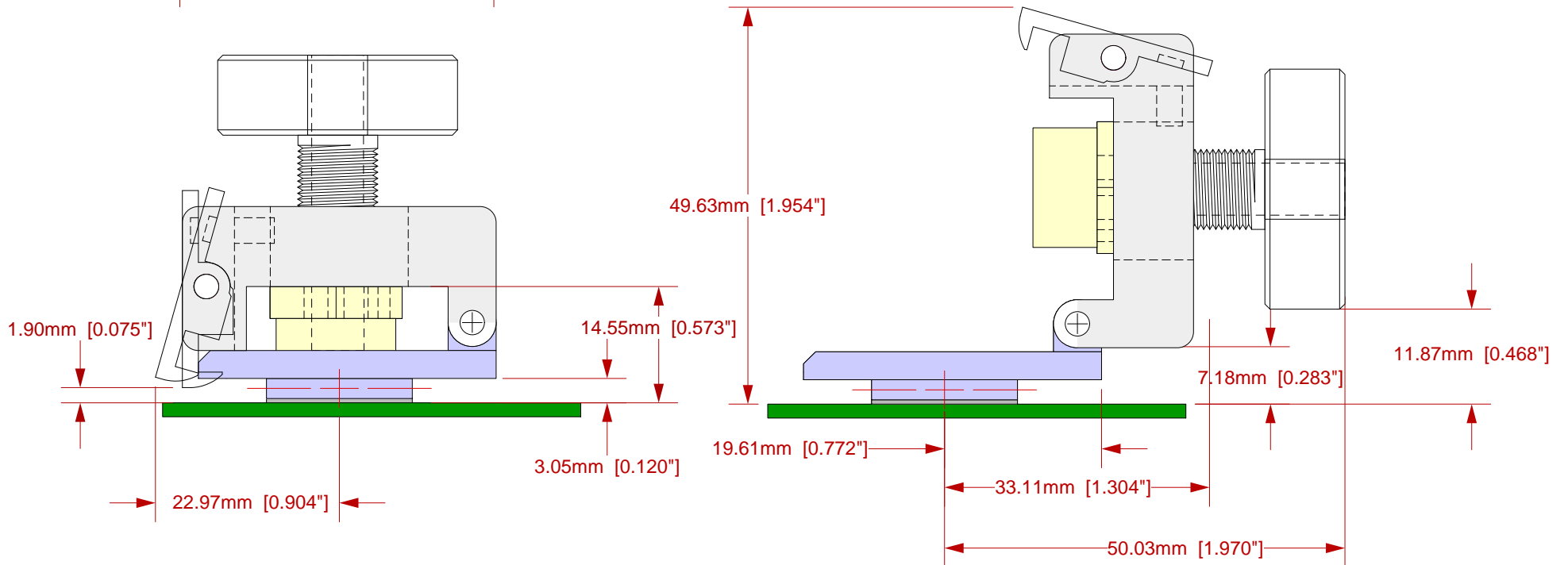
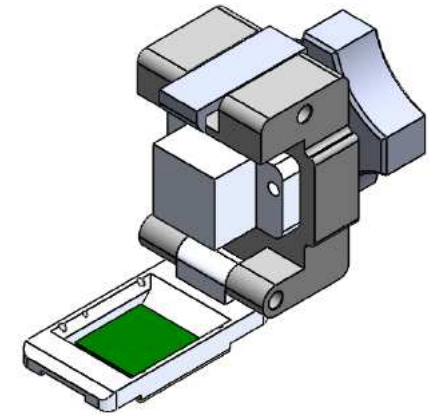
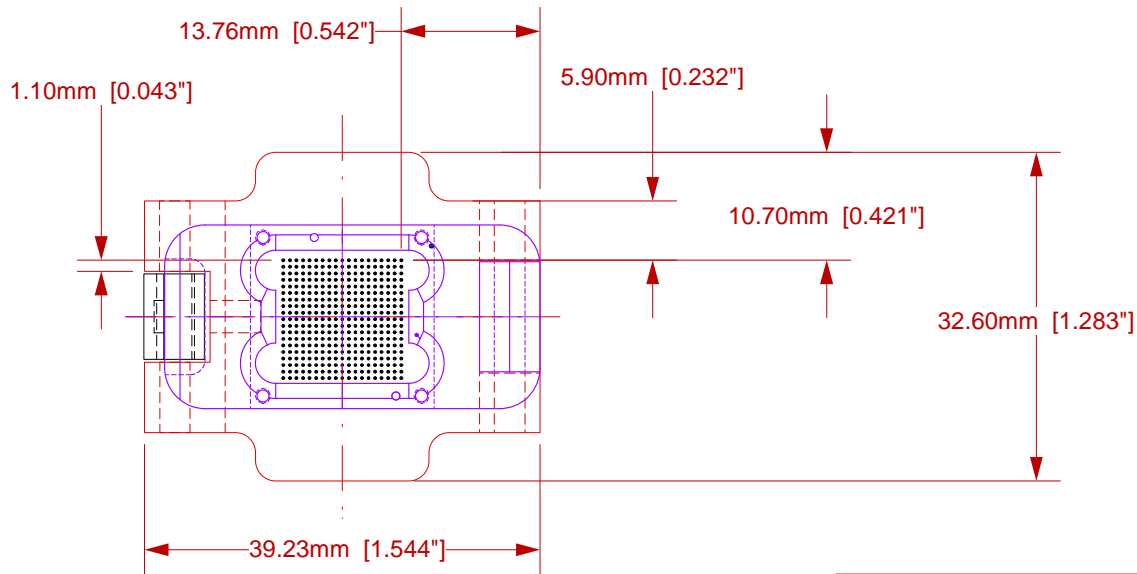


Side View


Description: Backing Plate

<p>CG-BGA-5008 Drawing</p>	<p>Status: Released</p>	<p>Scale: 1.25:1</p>	<p>Rev: A</p>
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<p>File: CG-BGA-5008 Dwg</p>		<p>Modified:</p>	

All dimensions are in mm.
All tolerances are +/- 0.125mm.
(Unless stated otherwise)



Description: Keep out area information

	CG-BGA-5008 Drawing	Status: Released	Scale: 1.25:1	Rev: A
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		File: CG-BGA-5008 Dwg	Modified:	

All dimensions are in mm.
 All tolerances are +/- 0.125mm.
 (Unless stated otherwise)